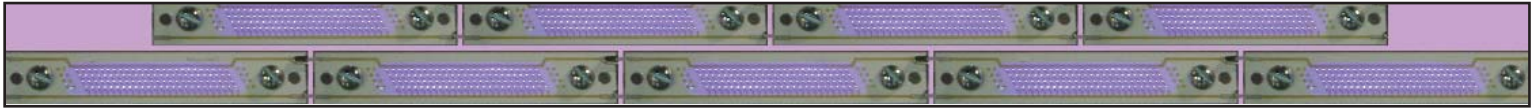


UV LED Cure-All™ Linear 100 Array



CON-TROL-CURE™ is proud to announce the 5th generation version of the patents-pending UV LED Cure-All™. This UV LED Linear Array lamp is now able to cure **opaque** inks, clear adhesives, thick opaque coatings, and fillers at astounding rates and is the first commercial UV LED curing system that **truly works**.

The unique geometry of the Linear Array enables continuous, uniform UV light of unlimited length for your curing application (see the above strip.)

FEATURES:

- Instant on/instant off
- Emits **no heat**- able to cure heat sensitive substrates
- Lamp life over **50,000 hours**
- Non-hazardous lamp
- Powered by universal power wall adapter
- Scalable-- can be made as big as needed (from 1"-1000')

TECHNICAL SPECIFICATIONS:

This device is a rectangular chip-on-board (COB) assembly containing 100 ultraviolet die. The board measures 3.95" x 0.75" and is .0625" thick Porcelain Coated Steel with a special white coating to maximize light extraction. It utilizes COB technology to maximize chip density and a metal core substrate for high thermal conductivity. The special surface coating significantly increases light extraction and does not degrade due to environmental extremes. Intended use is curing of UV curable materials.

Flux Characteristics at Maximum Rated Forward Current

T_A = 25°C

TYPE	RADIANT FLUX (φ _E , mW)	FORWARD CURRENT (I _F , mA)
395 nm	1050	1250

Electro-Optical

T_A = 25°C, I_F=500mA

	MIN	TYP	MAX
RADIANT FLUX (φ _E)	400mW		500mW
FORWARD VOLTAGE (V _F)	14.8V		16V
PEAK WAVELENGTH (λ _p)	390nm	395nm	400nm

General

T_A = 25°C

TYPICAL POWER CONSUMPTION	7.4W	MAXIMUM FORWARD CURRENT	1250mA (50mA/die)
MAXIMUM POWER CONSUMPTION	15.4W	JUNCTION TEMPERATURE	<115°C

24-HOUR PRODUCT SERVICES

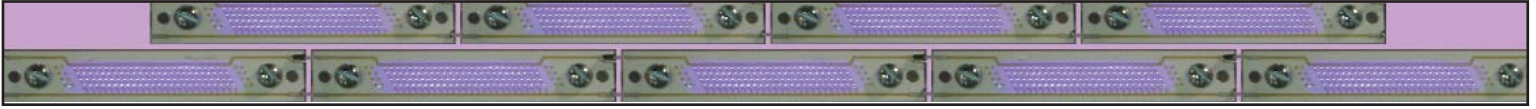
Internet: www.uvprocess.com

E-mail: info@uvps.com

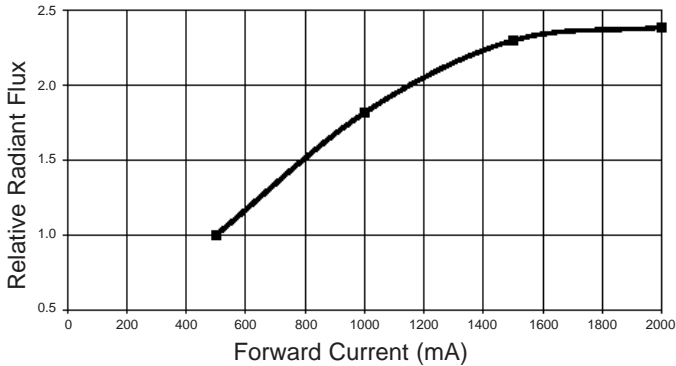


UVPS[®]
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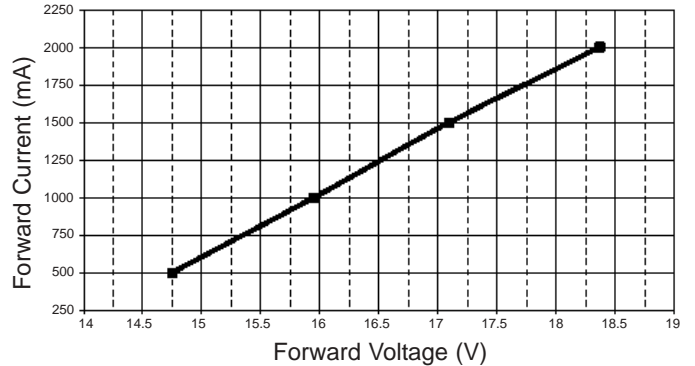
UV LED Cure-All™ Linear 100 Array



Relative Radiant Flux vs. Forward Current



Nominal Forward Voltage vs. Forward Current

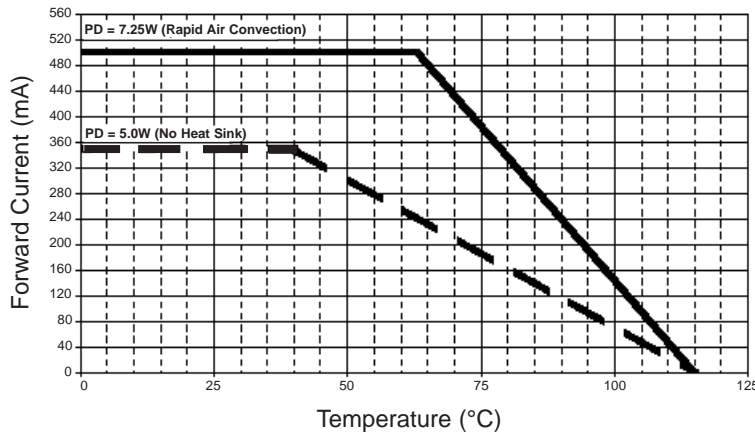


Thermal Considerations

Most applications will require the 100-die substrate to be attached to a heat-sinking surface. Care should be taken to ensure that the maximum junction temperature is not exceeded in the given application. Use the following information to design a thermal system using the 100-die substrate.

Maximum Junction Temperature	115°C
Thermal Resistance Junction-to-Case, R_{THJC} Rapid Air Convection	4.2°C/W
Thermal Resistance Junction-to-Ambient, R_{THJA} No Heat Sink / Still Air	14.9°C/W

Derating Forward Current vs. Temperature



24-HOUR PRODUCT SERVICES

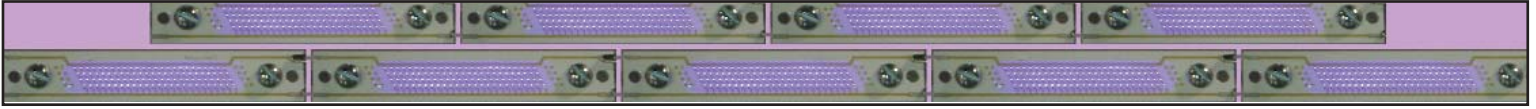
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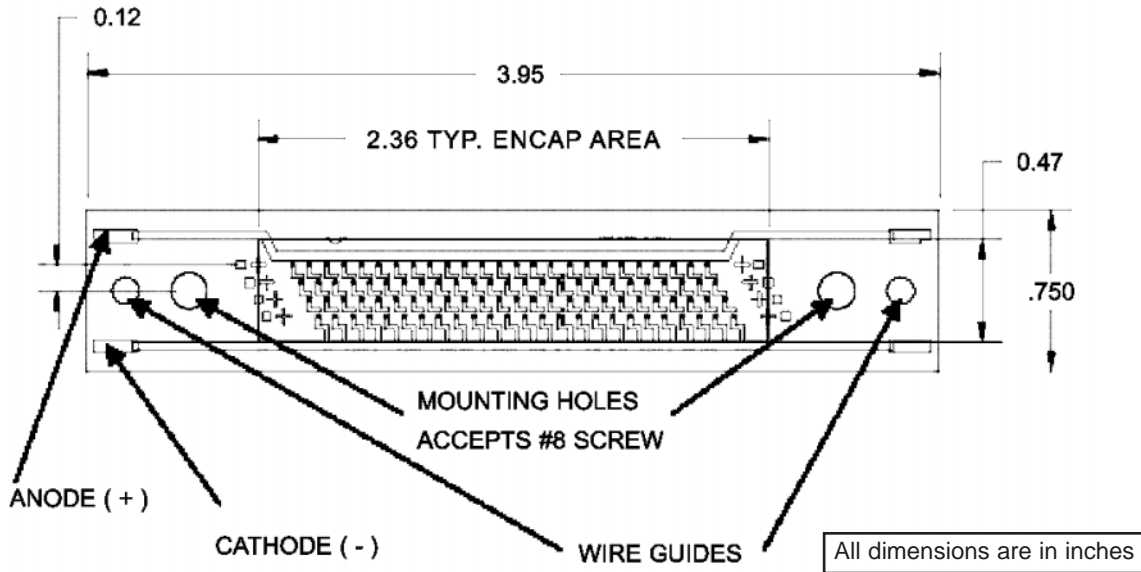


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UV LED Cure-All™ Linear 100 Array



Mechanical Detail



Mechanical / Electrical

Two mounting holes provided. (.169", #8 clearance)

Use #8 screws with shoulder washers to properly mount device

DO NOT USE STAR WASHERS – THEY MAY FRACTURE THE PORCELAIN COATING

Standard Current = 500mA

Compliance Voltage = 20 Volts

Maximum Ratings

$T_A = 25^\circ\text{C}$

Forward Current	1250 mA (Follow Derating Chart)
Power (Heat Sink Required)	30.0 W
Storage Temperature	-40°C to 120°C
Operating Temperature	-40°C to 100°C
Relative Humidity	90% Non Condensing
Junction Temperature	< 115°C
Thermal Resistance Junction-to-Ambient R_{THJA}	7.2°C/W (Forced Air Calculation)

Custom arrays are available. Contact us for more information.

24-HOUR PRODUCT SERVICES

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E-mail: info@uvps.com



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